Renesas Electronics America Inc - M306NNFJGP#U3 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	24MHz
Connectivity	CANbus, I²C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	111
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LFQFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m306nnfjgp-u3

M16C/6N Group (M16C/6NL, M16C/6NN)

Renesas MCU

REJ03B0061-0210
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1. Overview

The M16C/6N Group (M16C/6NL, M16C/6NN) of MCUs are built using the high-performance silicon gate CMOS process using the M16C/60 Series CPU core and are packaged in 100-pin and 128-pin plastic molded LQFP. These MCUs operate using sophisticated instructions featuring a high level of instruction efficiency. With 1 Mbyte of address space, they are capable of executing instructions at high speed. Being equipped with one CAN (Controller Area Network) module in the M16C/6N Group (M16C/6NL, M16C/6NN), the MCU is suited to drive automotive and industrial control systems. The CAN module complies with the 2.0B specification. In addition, this MCU contains a multiplier and DMAC which combined with fast instruction processing capability, makes it suitable for control of various OA, communication equipment which requires high-speed arithmetic/logic operations.

1.1 Applications

- Car audio and industrial control systems, other

Specifications written in this manual are believed to be accurate, but are not guaranteed to be entirely free of error. Specifications in this manual may be changed for functional or performance improvements. Please make sure your manual is the latest edition.

1.2 Performance Overview

Tables 1.1 and 1.2 list the Functions and Specifications for M16C/6N Group (M16C/6NL, M16C/6NN).

Table 1.1 Functions and Specifications for M16C/6N Group (100-pin Version: M16C/6NL)

Item			Specification
CPU	Number of fundamental instructions		91 instructions
	Minimum instruction execution time		41.7ns (f(BCLK) = 24 MHz, 1/1 prescaler, without software wait)
	Operating mode		Single-chip, memory expansion and microprocessor modes
	Address space		1 Mbyte
	Memory capacity		Refer to **Table 1.3 Product Information**
Peripheral Function	Ports		Input/Output: 87 pins, Input: 1 pin
	Multifunction timers		Timer A: 16 bits × 5 channels Timer B: 16 bits × 6 channels Three-phase motor control circuit
	Serial interfaces		3 channels Clock synchronous, UART, I²C-bus (1), IEBus (2) 2 channels Clock synchronous
	A/D converter		10-bit A/D converter: 1 circuit, 26 channels
	D/A converter		8 bits × 2 channels
	DMAC		2 channels
	CRC calculation circuit		CRC-CCITT
	CAN module		1 channel with 2.0B specification
	Watchdog timer		15 bits × 1 channel (with prescaler)
	Interrupts		Internal: 30 sources, External: 9 sources Software: 4 sources, Priority levels: 7 levels
	Clock generation circuits		4 circuits • Main clock oscillation circuit (*) • Sub clock oscillation circuit (*) • On-chip oscillator • PLL frequency synthesizer (*) Equipped with on-chip feedback resistor
	Oscillation-stopped detector		Main clock oscillation stop and re-oscillation detection function
Electrical Characteristics	Supply voltage		VCC = 3.0 to 5.5 V (f(BCLK) = 24 MHz, 1/1 prescaler, without software wait)
	Consumption current	Mask ROM	19mA (f(BCLK) = 24 MHz, PLL operation, no division)
		Flash memory	21mA (f(BCLK) = 24 MHz, PLL operation, no division)
		Mask ROM	3µA (f(BCLK) = 32 kHz, Wait mode, Oscillation capacity Low)
		Flash memory	0.8µA (Stop mode, Topr = 25°C)
Flash Memory Version	Programming and erasure voltage		3.3 ± 0.3 V or 5.0 ± 0.5 V
	Programming and erasure endurance		100 times
I/O Characteristics	I/O withstand voltage		5.0 V
	Output current		5m A
Operating Ambient Temperature			-40 to 85°C
Device Configuration			CMOS high-performance silicon gate
Package			100-pin molded-plastic LQFP

NOTES:

1. I²C-bus is a trademark of Koninklijke Philips Electronics N.V.
2. IEBus is a trademark of NEC Electronics Corporation.

Table 1.7 List of Pin Names for 128-Pin Package (2)

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	CAN Module Pin	Bus Control Pin
51		P5_6						ALE
52		P5_5						$\overline{\text{HOLD}}$
53		P5_4						$\overline{\text{HLDA}}$
54		P13_3						
55		P13_2						
56		P13_1						
57		P13_0						
58		P5_3						BCLK
59		P5_2						$\overline{\text{RD}}$
60		P5_1						$\overline{\text{WRH/BHE}}$
61		P5_0						$\overline{\text{WRL/WR}}$
62		P12_7						
63		P12_6						
64		P12_5						
65		P4_7						$\overline{\text{CS3}}$
66		P4_6						$\overline{\text{CS2}}$
67		P4_5						$\overline{\text{CS1}}$
68		P4_4						$\overline{\text{CS0}}$
69		P4_3						A19
70		P4_2						A18
71		P4_1						A17
72		P4_0						A16
73		P3_7						A15
74		P3_6						A14
75		P3_5						A13
76		P3_4						A12
77		P3_3						A11
78		P3_2						A10
79		P3_1						A9
80		P12_4						
81		P12_3						
82		P12_2						
83		P12_1						
84		P12_0						
85	VCC2							
86		P3_0						A8(/-/D7)
87	VSS							
88		P2_7				AN2_7		A7(/D7/D6)
89		P2_6				AN2_6		A6(/D6/D5)
90		P2_5				AN2_5		A5(/D5/D4)
91		P2_4				AN2_4		A4(/D4/D3)
92		P2_3				AN2_3		A3(/D3/D2)
93		P2_2				AN2_2		A2(/D2/D1)
94		P2_1				AN2_1		A1(/D1/D0)
95		P2_0				AN2_0		A0(/D0/-)
96		P1_7	$\overline{\text{INT5}}$					D15
97		P1_6	$\overline{\text{INT4}}$					D14
98		P1_5	$\overline{\text{INT3}}$					D13
99		P1_4						D12
100		P1_3						D11

1.6 Pin Functions

Tables 1.9 to 1.11 list the Pin Functions.

Table 1.9 Pin Functions (100-pin and 128-pin Versions) (1)

Signal Name	Pin Name	I/O Type	Description
Power supply input	VCC1, VCC2, VSS	I	Apply 3.0 to 5.5 V to the VCC1 and VCC2 pins and 0 V to the VSS pin. The VCC apply condition is that VCC2 = VCC1 (1).
Analog power supply input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect the AVCC pin to VCC1. Connect the AVSS pin to VSS.
Reset input	RESET	I	The MCU is in a reset state when applying "L" to the this pin.
CNVSS	CNVSS	I	Switches processor mode. Connect this pin to VSS to when after a reset to start up in single-chip mode. Connect this pin to VCC1 to start up in microprocessor mode.
External data bus width select input	BYTE	I	Switches the data bus in external memory space. The data bus is 16-bit long when the this pin is held "L" and 8-bit long when the this pin is held "H". Set it to either one. Connect this pin to VSS when single-chip mode.
Bus control pins	D0 to D7	I/O	Inputs and outputs data (D0 to D7) when these pins are set as the separate bus.
	D8 to D15	I/O	Inputs and outputs data (D8 to D15) when external 16-bit data bus is set as the separate bus.
	A0 to A19	O	Output address bits (A0 to A19).
	A0/D0 to A7/D7	I/O	Input and output data (D0 to D7) and output address bits (A0 to A7) by time-sharing when external 8-bit data bus are set as the multiplexed bus.
	A1/D0 to A8/D7	I/O	Input and output data (D0 to D7) and output address bits (A1 to A8) by time-sharing when external 16-bit data bus are set as the multiplexed bus.
	$\overline{CS0}$ to $\overline{CS3}$	O	Output $\overline{CS0}$ to $\overline{CS3}$ signals. $\overline{CS0}$ to $\overline{CS3}$ are chip-select signals to specify an external space.
	$\overline{WRL}$/$\overline{WR}$ $\overline{WRH}$/$\overline{BHE}$ $\overline{RD}$	O	Output $\overline{WRL}$, $\overline{WRH}$, ($\overline{WR}$, $\overline{BHE}$), $\overline{RD}$ signals. $\overline{WRL}$ and $\overline{WRH}$ or $\overline{BHE}$, and $\overline{WR}$ can be switched by program. • $\overline{WRL}$, $\overline{WRH}$, and $\overline{RD}$ are selected The $\overline{WRL}$ signal becomes "L" by writing data to an even address in an external memory space. The $\overline{WRH}$ signal becomes "L" by writing data to an odd address in an external memory space. The $\overline{RD}$ pin signal becomes "L" by reading data in an external memory space. • $\overline{WR}$, $\overline{BHE}$, and $\overline{RD}$ are selected The $\overline{WR}$ signal becomes "L" by writing data in an external memory space. The $\overline{RD}$ signal becomes "L" by reading data in an external memory space. The $\overline{BHE}$ signal becomes "L" by accessing an odd address. Select $\overline{WR}$, $\overline{BHE}$, and $\overline{RD}$ for an external 8-bit data bus.
	$\overline{ALE}$	O	$\overline{ALE}$ is a signal to latch the address.
	$\overline{HOLD}$	I	While the $\overline{HOLD}$ pin is held "L", the MCU is placed in a hold state.
	$\overline{HLDA}$	O	In a hold state, $\overline{HLDA}$ outputs a "L" signal.
	$\overline{RDY}$	I	While applying a "L" signal to the $\overline{RDY}$ pin, the MCU is placed in a wait state.

I: Input O: Output I/O: Input/Output

NOTE:
1. In this manual, hereafter, VCC refers to VCC1 unless otherwise noted.

Table 1.10 Pin Functions (100-pin and 128-pin Versions) (2)

Signal Name	Pin Name	I/O Type	Description
Main clock input	XIN	I	I/O pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT (1).
Main clock output	XOUT	O	To use the external clock, input the clock from XIN and leave XOUT open.
Sub clock input	XCIN	I	I/O pins for a sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT (1).
Sub clock output	XCOUT	O	To use the external clock, input the clock from XCIN and leave XCOUT open.
BCLK output	BCLK	O	Outputs the BCLK signal.
Clock output	CLKOUT	O	The clock of the same cycle as fC, f8, or f32 is output.
INT interrupt input	INT0 to INT8 (2)	I	Input pins for the INT interrupt.
NMI interrupt input	NMI	I	Input pin for the NMI interrupt.
Key input interrupt input	KI0 to KI3	I	Input pins for the key input interrupt.
Timer A	TA0OUT to TA4OUT	I/O	These are timer A0 to timer A4 I/O pins.
	TA0IN to TA4IN	I	These are timer A0 to timer A4 input pins.
	ZP	I	Input pin for the Z-phase.
Timer B	TB0IN to TB5IN	I	These are timer B0 to timer B5 input pins.
Three-phase motor control output	U, U, V, V, W, W	O	These are Three-phase motor control output pins.
Serial interface	CTS0 to CTS2	I	These are transmit control input pins.
	RTS0 to RTS2	O	These are receive control output pins.
	CLK0 to CLK6 (2)	I/O	These are transfer clock I/O pins.
	RXD0 to RXD2	I	These are serial data input pins.
	SIN3 to SIN6 (2)	I	These are serial data input pins.
	TXD0 to TXD2	O	These are serial data output pins.
	SOUT3 to SOUT6 (2)	O	These are serial data output pins.
	CLKS1	O	This is output pin for transfer clock output from multiple pins function.
I^2C mode	SDA0 to SDA2	I/O	These are serial data I/O pins.
	SCL0 to SCL2	I/O	These are transfer clock I/O pins. (however, SCL2 for the N-channel open drain output.)
Reference voltage input	VREF	I	Applies the reference voltage for the A/D converter and D/A converter.
A/D converter	AN0 to AN7 AN0_0 to AN0_7 AN2_0 to AN2_7	I	Analog input pins for the A/D converter.
	ADTRG	I	This is an A/D trigger input pin.
	ANEX0	I/O	This is the extended analog input pin for the A/D converter, and is the output in external op-amp connection mode.
	ANEX1	I	This is the extended analog input pin for the A/D converter.
D/A converter	DA0, DA1	O	These are the output pins for the D/A converter.
CAN module	CRX0	I	This is the input pin for the CAN module.
	CTX0	O	This is the output pin for the CAN module.

I: Input O: Output I/O: Input/Output

NOTES:
1. Ask the oscillator maker the oscillation characteristic.
2. INT6 to INT8, CLK5, CLK6, SIN5, SIN6, SOUT5, SOUT6 are only in the 128-pin version.

Table 4.4 SFR Information (4)

Address	Register	Symbol	After Reset
00C0h	CAN0 Message Box 6: Identifier / DLC		XXh
00C1h			XXh
00C2h			XXh
00C3h			XXh
00C4h			XXh
00C5h			XXh
00C6h	CAN0 Message Box 6: Data Field		XXh
00C7h			XXh
00C8h			XXh
00C9h			XXh
00CAh			XXh
00CBh			XXh
00CCh			XXh
00CDh			XXh
00CEh	CAN0 Message Box 6: Time Stamp		XXh
00CFh			XXh
00D0h	CAN0 Message Box 7: Identifier / DLC		XXh
00D1h			XXh
00D2h			XXh
00D3h			XXh
00D4h			XXh
00D5h			XXh
00D6h	CAN0 Message Box 7: Data Field		XXh
00D7h			XXh
00D8h			XXh
00D9h			XXh
00DAh			XXh
00DBh			XXh
00DCh			XXh
00DDh			XXh
00DEh	CAN0 Message Box 7: Time Stamp		XXh
00DFh			XXh
00E0h	CAN0 Message Box 8: Identifier / DLC		XXh
00E1h			XXh
00E2h			XXh
00E3h			XXh
00E4h			XXh
00E5h			XXh
00E6h	CAN0 Message Box 8: Data Field		XXh
00E7h			XXh
00E8h			XXh
00E9h			XXh
00EAh			XXh
00EBh			XXh
00ECh			XXh
00EDh			XXh
00EEh	CAN0 Message Box 8: Time Stamp		XXh
00EFh			XXh
00F0h	CAN0 Message Box 9: Identifier / DLC		XXh
00F1h			XXh
00F2h			XXh
00F3h			XXh
00F4h			XXh
00F5h			XXh
00F6h	CAN0 Message Box 9: Data Field		XXh
00F7h			XXh
00F8h			XXh
00F9h			XXh
00FAh			XXh
00FBh			XXh
00FCh			XXh
00FDh			XXh
00FEh	CAN0 Message Box 9: Time Stamp		XXh
00FFh			XXh

X: Undefined

Table 4.7 SFR Information (7) [2]

Address	Register	Symbol	After Reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h			
01B4h			
01B5h	Flash Memory Control Register 1 [1]	FMR1	0X00XX0Xb
01B6h			
01B7h	Flash Memory Control Register 0 [1]	FMR0	00000001b
01B8h	Address Match Interrupt Register 2	RMAD2	00h
01B9h			00h
01BAh			X0h
01BBh	Address Match Interrupt Enable Register 2	AIER2	XXXXXX00b
01BCh	Address Match Interrupt Register 3	RMAD3	00h
01BDh			00h
01BEh			X0h
01BFh			

X: Undefined

NOTES:
1. These registers are included in the flash memory version. Cannot be accessed by users in the mask ROM version.
2. Blank spaces are reserved. No access is allowed.

Table 4.8 SFR Information (8) (3)

Address	Register	Symbol	After Reset
01C0h	Timer B3, B4, B5 Count Start Flag	TBSR	000XXXXXb
01C1h			
01C2h	Timer A1-1 Register	TA11	XXh
01C3h			XXh
01C4h	Timer A2-1 Register	TA21	XXh
01C5h			XXh
01C6h	Timer A4-1 Register	TA41	XXh
01C7h			XXh
01C8h	Three-Phase PWM Control Register 0	INVC0	00h
01C9h	Three-Phase PWM Control Register 1	INVC1	00h
01CAh	Three-Phase Output Buffer Register 0	IDB0	00111111b
01CBh	Three-Phase Output Buffer Register 1	IDB1	00111111b
01CCh	Dead Time Timer	DTT	XXh
01CDh	Timer B2 Interrupt Generation Frequency Set Counter	ICTB2	XXh
01CEh			
01CFh	Interrupt Source Select Register 2	IFSR2	X0000000b
01D0h	Timer B3 Register	TB3	XXh
01D1h			XXh
01D2h	Timer B4 Register	TB4	XXh
01D3h			XXh
01D4h	Timer B5 Register	TB5	XXh
01D5h			XXh
01D6h	SI/O6 Transmit/Receive Register (1)	S6TRR	XXh
01D7h			
01D8h	SI/O6 Control Register (1)	S6C	01000000b
01D9h	SI/O6 Bit Rate Register (1)	S6BRG	XXh
01DAh	SI/O3, 4, 5, 6 Transmit/Receive Register (2)	S3456TRR	XXXX0000b
01DBh	Timer B3 Mode Register	TB3MR	00XX0000b
01DCh	Timer B4 Mode Register	TB4MR	00XX0000b
01DDh	Timer B5 Mode Register	TB5MR	00XX0000b
01DEh	Interrupt Source Select Register 0	IFSR0	00h
01DFh	Interrupt Source Select Register 1	IFSR1	00h
01E0h	SI/O3 Transmit/Receive Register	S3TRR	XXh
01E1h			
01E2h	SI/O3 Control Register	S3C	01000000b
01E3h	SI/O3 Bit Rate Register	S3BRG	XXh
01E4h	SI/O4 Transmit/Receive Register	S4TRR	XXh
01E5h			
01E6h	SI/O4 Control Register	S4C	01000000b
01E7h	SI/O4 Bit Rate Register	S4BRG	XXh
01E8h	SI/O5 Transmit/Receive Register (1)	S5TRR	XXh
01E9h			
01EAh	SI/O5 Control Register (1)	S5C	01000000b
01EBh	SI/O5 Bit Rate Register (1)	S5BRG	XXh
01ECh	UART0 Special Mode Register 4	U0SMR4	00h
01EDh	UART0 Special Mode Register 3	U0SMR3	000X0X0Xb
01EEh	UART0 Special Mode Register 2	U0SMR2	X0000000b
01EFh	UART0 Special Mode Register	U0SMR	X0000000b
01F0h	UART1 Special Mode Register 4	U1SMR4	00h
01F1h	UART1 Special Mode Register 3	U1SMR3	000X0X0Xb
01F2h	UART1 Special Mode Register 2	U1SMR2	X0000000b
01F3h	UART1 Special Mode Register	U1SMR	X0000000b
01F4h	UART2 Special Mode Register 4	U2SMR4	00h
01F5h	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
01F6h	UART2 Special Mode Register 2	U2SMR2	X0000000b
01F7h	UART2 Special Mode Register	U2SMR	X0000000b
01F8h	UART2 Transmit/Receive Mode Register	U2MR	00h
01F9h	UART2 Bit Rate Register	U2BRG	XXh
01FAh	UART2 Transmit Buffer Register	U2TB	XXh
01FBh			XXh
01FCh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
01FDh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
01FEh	UART2 Receive Buffer Register	U2RB	XXh
01FFh			XXh

X: Undefined

NOTES:
1. These registers exist only in the 128-pin version.
2. Bits S5TRF and S6TRF in the S3456TRR register are used in the 128-pin version.
3. Blank spaces are reserved. No access is allowed.

Table 5.3 Recommended Operating Conditions (2) (1)

Symbol	Parameter				Standard			Unit
					Min.	Typ.	Max.	
f(XIN)	Main clock input oscillation frequency (2) (3) (4)	No wait	Mask ROM version Flash memory version	VCC = 3.0 to 5.5 V	0		16	MHz
f(XCIN)	Sub clock oscillation frequency					32.768	50	kHz
f(Ring)	On-chip oscillation frequency					1		MHz
f(PLL)	PLL clock oscillation frequency				16		24	MHz
f(BCLK)	CPU operation clock			VCC = 3.0 to 5.5 V	0		24	MHz
$t_{su(PLL)}$	PLL frequency synthesizer stabilization wait time						20	ms

NOTES:

1. Referenced to VCC = 3.0 to 5.5 V at Topr = –40 to 85°C unless otherwise specified.
2. Relationship between main clock oscillation frequency and supply voltage is shown right.
3. Execute program/erase of flash memory by VCC = 3.3 ± 0.3 V or VCC = 5.0 ± 0.5 V.
4. When using 16 MHz and over, use PLL clock. PLL clock oscillation frequency which can be used is 16 MHz, 20 MHz or 24 MHz.

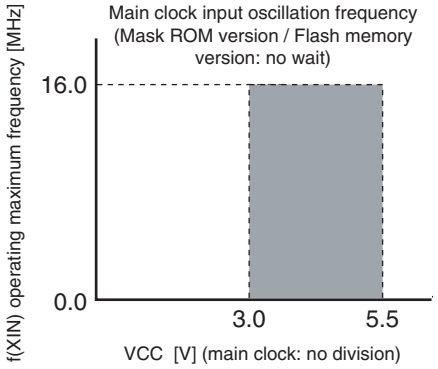


Table 5.6 A/D Conversion Characteristics (1)

Symbol	Parameter		Measuring Condition		Standard Min.	Standard Typ.	Standard Max.	Unit
–	Resolution		VREF = VCC				10	Bit
INL	Integral nonlinearity error	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
			VREF = VCC = 3.3 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±5	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 3.3 V				±2	LSB
–	Absolute accuracy	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
			VREF = VCC = 3.3 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±5	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 3.3 V				±2	LSB
DNL	Differential nonlinearity error						±1	LSB
–	Offset error						±3	LSB
–	Gain error						±3	LSB
R_{LADDER}	Resistor ladder		VREF = VCC		10		40	kΩ
t_{CONV}	10-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		3.3			µs
	8-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		2.8			µs
t_{SAMP}	Sampling time				0.3			µs
V_{REF}	Reference voltage				2.0		V_{CC}	V
V_{IA}	Analog input voltage				0		V_{REF}	V

NOTES:
1. Referenced to VCC = AVCC = VREF = 3.3 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. ϕAD frequency must be 10 MHz or less.
3. When sample & hold is disabled, ϕAD frequency must be 250 kHz or more in addition to a limit of NOTE 2.
   When sample & hold is enabled, ϕAD frequency must be 1 MHz or more in addition to a limit of NOTE 2.

Table 5.7 D/A conversion Characteristics (1)

Symbol	Parameter	Measuring Condition	Standard Min.	Standard Typ.	Standard Max.	Unit
–	Resolution				8	Bits
–	Absolute accuracy				1.0	%
t_{su}	Setup time				3	µs
R_O	Output resistance		4	10	20	kΩ
I_{VREF}	Reference power supply input current	(NOTE 2)			1.5	mA

NOTES:
1. Referenced to VCC = AVCC = VREF = 3.3 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. This applies when using one D/A converter, with the DAi register (i = 0, 1) for the unused D/A converter set to 00h.
   The resistor ladder of the A/D converter is not included. Also, the I_{VREF} will flow even if VREF is disconnected by the ADCON1 register.

Table 5.8 Flash Memory Version Electrical Characteristics (1)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
-	Programming and erasure endurance (2)		100			cycle
-	Word program time (VCC = 5.0 V)			25	200	µs
-	Lock bit program time			25	200	µs
-	Block erase time (VCC = 5.0 V)	4-Kbyte block		0.3	4	s
		8-Kbyte block		0.3	4	s
		32-Kbyte block		0.5	4	s
		64-Kbyte block		0.8	4	s
-	Erase all unlocked blocks time				4 × n (3)	s
tps	Flash memory circuit stabilization wait time				15	µs

NOTES:
1. Referenced to VCC = 4.5 to 5.5 V, 3.0 to 3.6 V, Topr = 0 to 60°C unless otherwise specified.
2. Programming and erasure endurance refers to the number of times a block erase can be performed.
   If the programming and erasure endurance is n (n = 100), each block can be erased n times.
   For example, if a 4-Kbyte block A is erased after writing 1 word data 2,048 times, each to a different address, this counts as one programming and erasure endurance. Data cannot be written to the same address more than once without erasing the block (rewrite prohibited).
3. n denotes the number of blocks to erase.

Table 5.9 Flash Memory Version Program/Erase Voltage and Read Operation Voltage Characteristics (at Topr = 0 to 60°C)

Flash Program, Erase Voltage	Flash Read Operation Voltage
VCC = 3.3 ± 0.3 V or 5.0 ± 0.5 V	VCC = 3.0 to 5.5 V

Table 5.10 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Measuring Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during powering-on	VCC = 3.0 to 5.5 V			2	ms
$t_{d(R-S)}$	STOP release time				150	µs
$t_{d(W-S)}$	Low power dissipation mode wait mode release time				150	µs

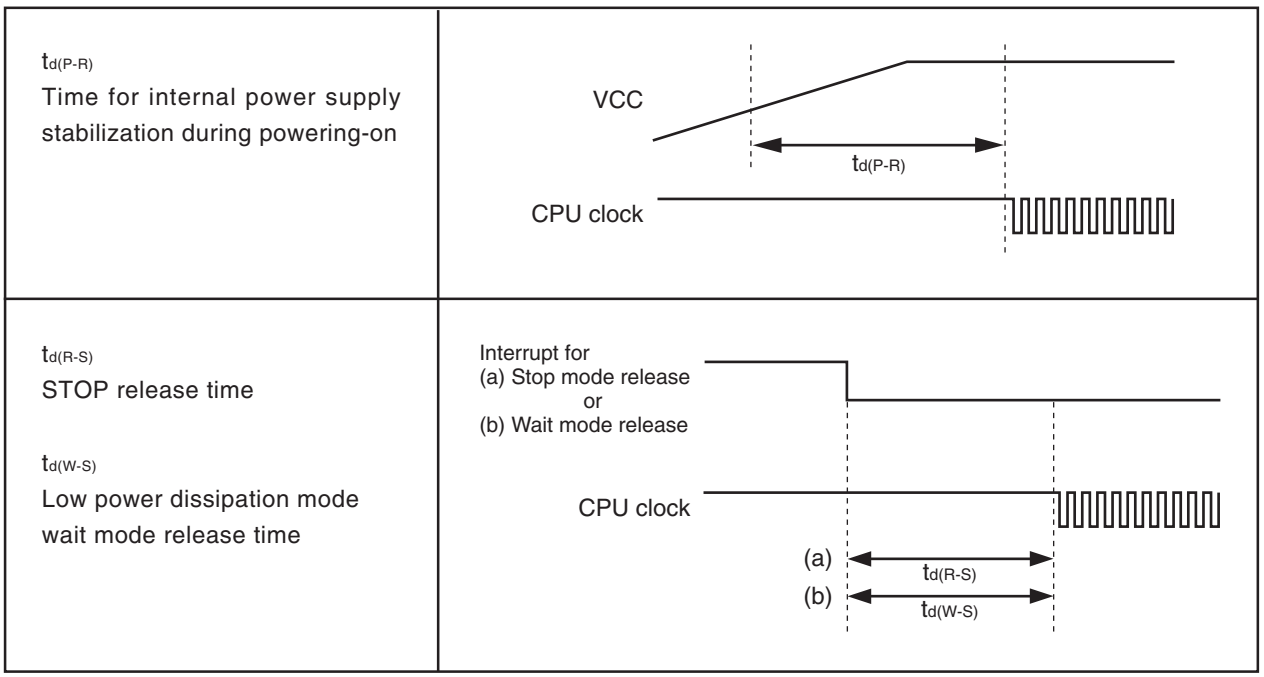


Figure 5.1 Power Supply Circuit Timing Diagram

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.11 External Clock Input (XIN Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	62.5		ns
$t_{w(H)}$	External clock input HIGH pulse width	25		ns
$t_{w(L)}$	External clock input LOW pulse width	25		ns
t_r	External clock rise time		15	ns
t_f	External clock fall time		15	ns

Table 5.12 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data input access time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data input access time (for setting with wait)		(NOTE 2)	ns
$t_{ac3(RD-DB)}$	Data input access time (when accessing multiplexed bus area)		(NOTE 3)	ns
$t_{su(DB-RD)}$	Data input setup time	40		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ input setup time	30		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ input setup time	40		ns
$t_{h(RD-DB)}$	Data input hold time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ input hold time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ input hold time	0		ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

n is “2” for 1-wait setting, “3” for 2-wait setting and “4” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

n is “2” for 2-wait setting, “3” for 3-wait setting.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.19 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	80		ns

Table 5.20 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.21 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.22 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{C(AD)}$	$\overline{\text{ADTRG}}$ input cycle time (trigger able minimum)	1000		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ input LOW pulse width	125		ns

Table 5.23 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TXDi output delay time		80	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	70		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

Table 5.24 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input HIGH pulse width	250		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input LOW pulse width	250		ns

Switching Characteristics VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.26 Memory Expansion Mode and Microprocessor Mode (for 1- to 3-wait setting and external area access)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.2		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		–4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (rin relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$

n is “1” for 1-wait setting, “2” for 2-wait setting and “3” for 3-wait setting. When n = 1, f(BCLK) is 12.5 MHz or less.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln (1 - V_{OL} / V_{CC})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2\ V_{CC}$, C = 30 pF, R =1 kΩ, hold time of output “L” level is
$t = -30\text{ pF} \times 1\text{ k}\Omega \times \ln (1 - 0.2\ V_{CC} / V_{CC}) = 6.7$ ns.

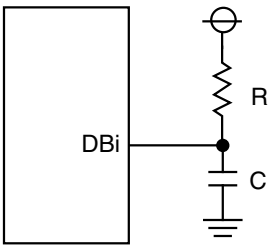


Table 5.28 Electrical Characteristics (1) **VCC = 3.3 V**

Symbol	Parameter			Measuring Condition	Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	HIGH output voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1		I_{OH} = –1 mA	V_{CC}-0.5		V_{CC}	V
V_{OH}	HIGH output voltage	XOUT	HIGHPOWER	I_{OH} = –0.1 mA	V_{CC}-0.5		V_{CC}	V
			LOWPOWER	I_{OH} = –50 µA	V_{CC}-0.5		V_{CC}	
	HIGH output voltage	XCOUT	HIGHPOWER	With no load applied		2.5		V
			LOWPOWER	With no load applied		1.6		
V_{OL}	LOW output voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1		I_{OL} = 1 mA			0.5	V
V_{OL}	LOW output voltage	XOUT	HIGHPOWER	I_{OL} = 0.1 mA			0.5	V
			LOWPOWER	I_{OL} = 50 µA			0.5	
	LOW output voltage	XCOUT	HIGHPOWER	With no load applied		0		V
			LOWPOWER	With no load applied		0		
V_{T+}-V_{T-}	Hysteresis	$\overline{HOLD}$, $\overline{RDY}$, TA0IN to TA4IN, TB0IN to TB5IN, $\overline{INT0}$ to $\overline{INT8}$, NMI, $\overline{ADTRG}$, $\overline{CTS0}$ to $\overline{CTS2}$, SCL0 to SCL2, SDA0 to SDA2, CLK0 to CLK6, TA0OUT to TA4OUT, $\overline{KI0}$ to $\overline{KI3}$, RXD0 to RXD2, SIN3 to SIN6			0.2		0.8	V
V_{T+}-V_{T-}	Hysteresis	$\overline{RESET}$			0.2		1.8	V
I_{IH}	HIGH input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1, XIN, $\overline{RESET}$, CNVSS, BYTE		V_I = 3.3 V			4.0	µA
I_{IL}	LOW input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1, XIN, $\overline{RESET}$, CNVSS, BYTE		V_I = 0 V			–4.0	µA
R_{PULLUP}	Pull-up resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1		V_I = 0 V	50	100	500	kΩ
R_{fXIN}	Feedback resistance	XIN				3.0		MΩ
R_{fXCIN}	Feedback resistance	XCIN				25		MΩ
V_{RAM}	RAM retention voltage			At stop mode	2.0			V

NOTES:
1. Referenced to VCC = 3.0 to 3.6 V, VSS = 0 V at Topr = –40 to 85°C, f(BCLK) = 24 MHz unless otherwise specified.
2. P11 to P14, $\overline{INT6}$ to $\overline{INT8}$, CLK5, CLK6, SIN5, and SIN6 are only in the 128-pin version.

Timing Requirements

VCC = 3.3 V

(Referenced to VCC = 3.3 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.31 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	150		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	60		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	60		ns

Table 5.32 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	600		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	300		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	300		ns

Table 5.33 Timer A Input (External Trigger Input in One-shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	300		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	150		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	150		ns

Table 5.34 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input HIGH pulse width	150		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	150		ns

Table 5.35 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT input cycle time	3000		ns
$t_{w(UPH)}$	TAiOUT input HIGH pulse width	1500		ns
$t_{w(UPL)}$	TAiOUT input LOW pulse width	1500		ns
$t_{su(UP-TIN)}$	TAiOUT input setup time	600		ns
$t_{h(TIN-UP)}$	TAiOUT input hold time	600		ns

Table 5.36 Timer A Input (Two-phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	2		µs
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	500		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	500		ns

Switching Characteristics VCC = 3.3 V

(Referenced to VCC = 3.3 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.45 Memory Expansion Mode and Microprocessor Mode (for 2- to 3-wait setting, external area access and multiplexed bus selection)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.11		50	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			50	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{h(RD-CS)}$	Chip select output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-CS)}$	Chip select output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			40	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			40	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			50	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time (in relation to BCLK)			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time (in relation to BCLK)		–4		ns
$t_{d(AD-ALE)}$	ALE signal output delay time (in relation to Address)		(NOTE 3)		ns
$t_{h(ALE-AD)}$	ALE signal output hold time (rin relation to Address)		(NOTE 4)		ns
$t_{d(AD-RD)}$	RD signal output delay from the end of Address		0		ns
$t_{d(AD-WR)}$	WR signal output delay from the end of Address		0		ns
$t_{dZ(RD-AD)}$	Address output floating start time			8	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 50 \text{ [ns]}$$

n is “2” for 2-wait setting, “3” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$

4. Calculated according to the BCLK frequency as follows:

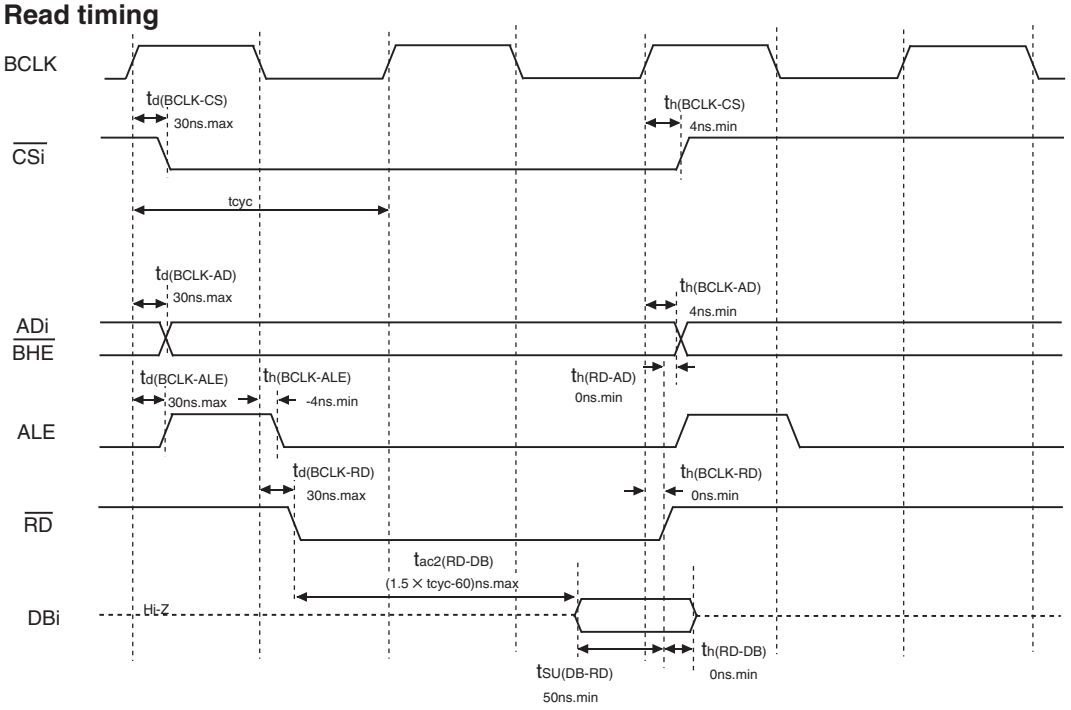
$$\frac{0.5 \times 10^9}{f(BCLK)} - 15 \text{ [ns]}$$

Memory Expansion Mode and Microprocessor Mode

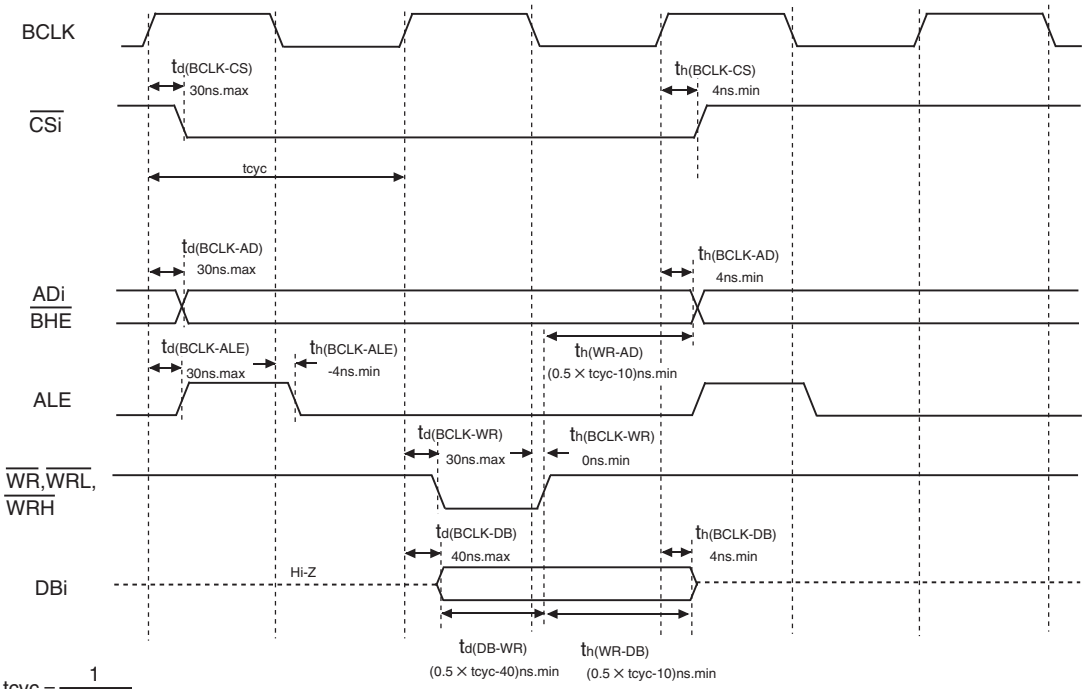
VCC = 3.3 V

(For 1-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

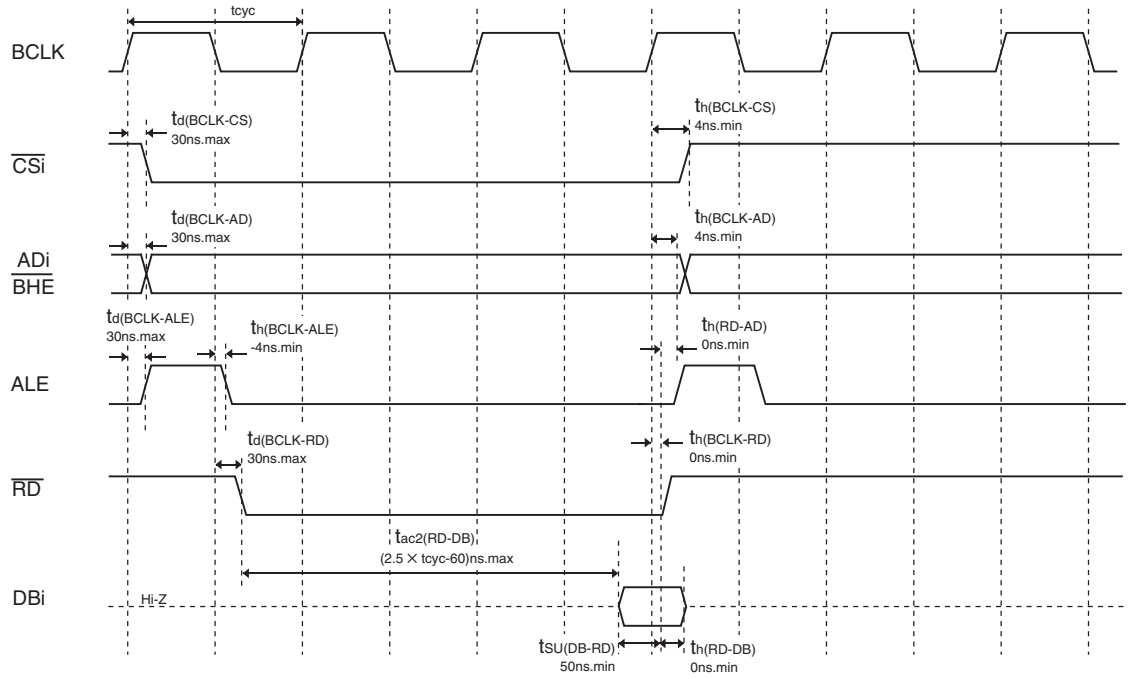
Figure 5.15 Timing Diagram (4)

Memory Expansion Mode and Microprocessor Mode

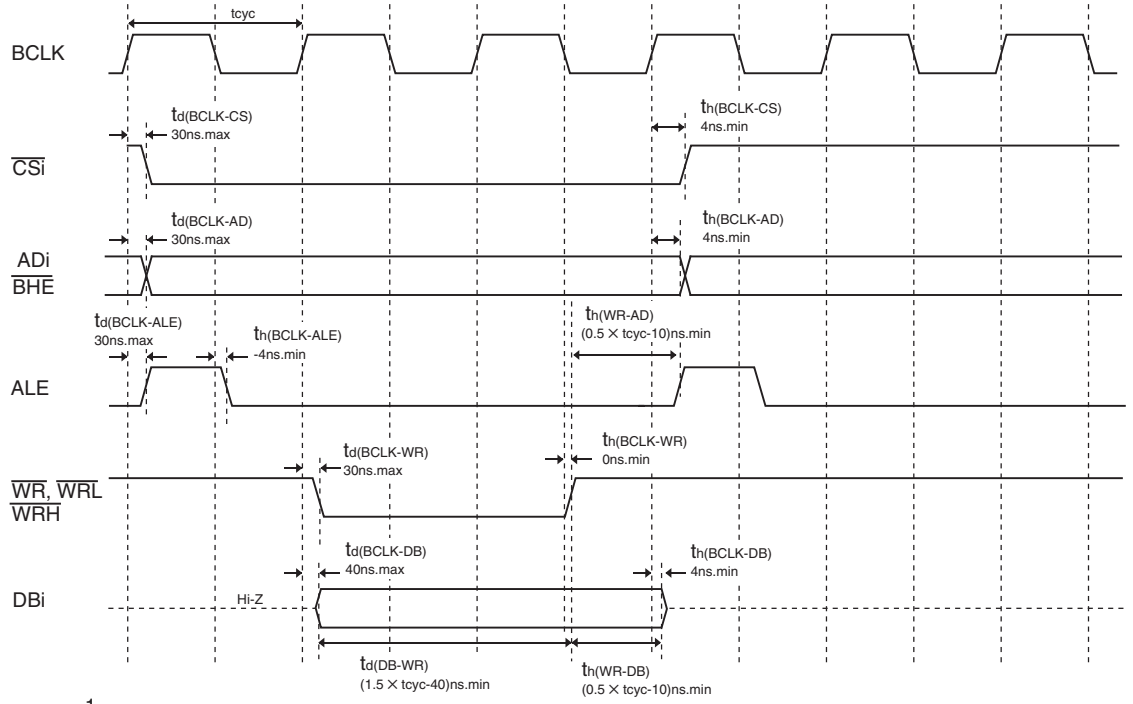
VCC = 3.3 V

(For 2-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

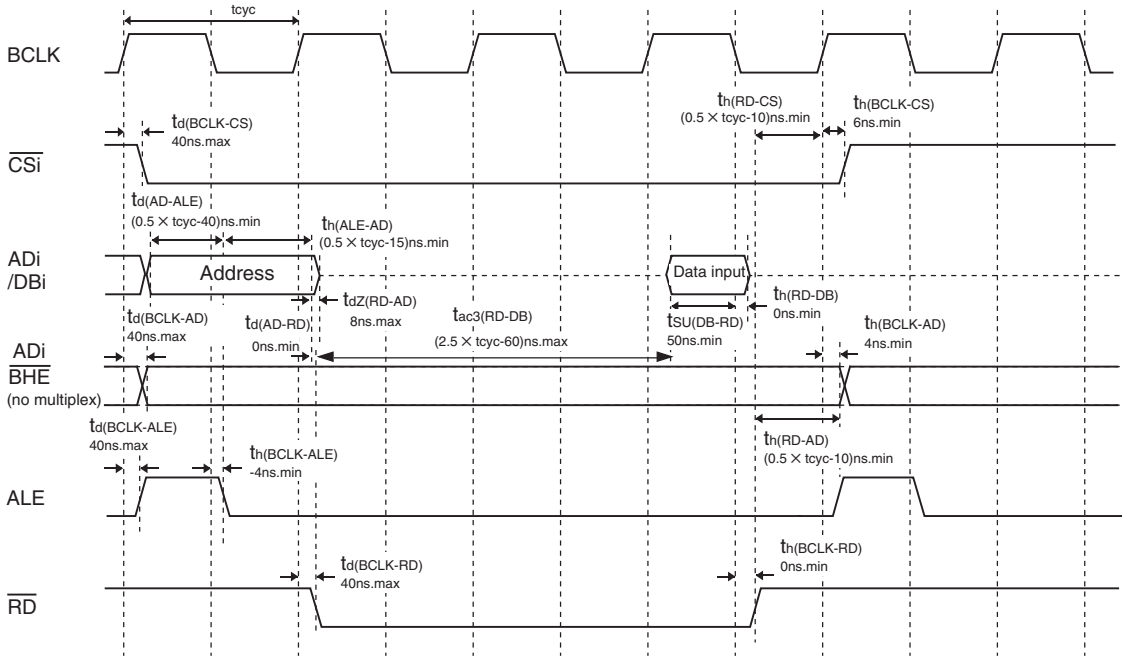
- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.16 Timing Diagram (5)

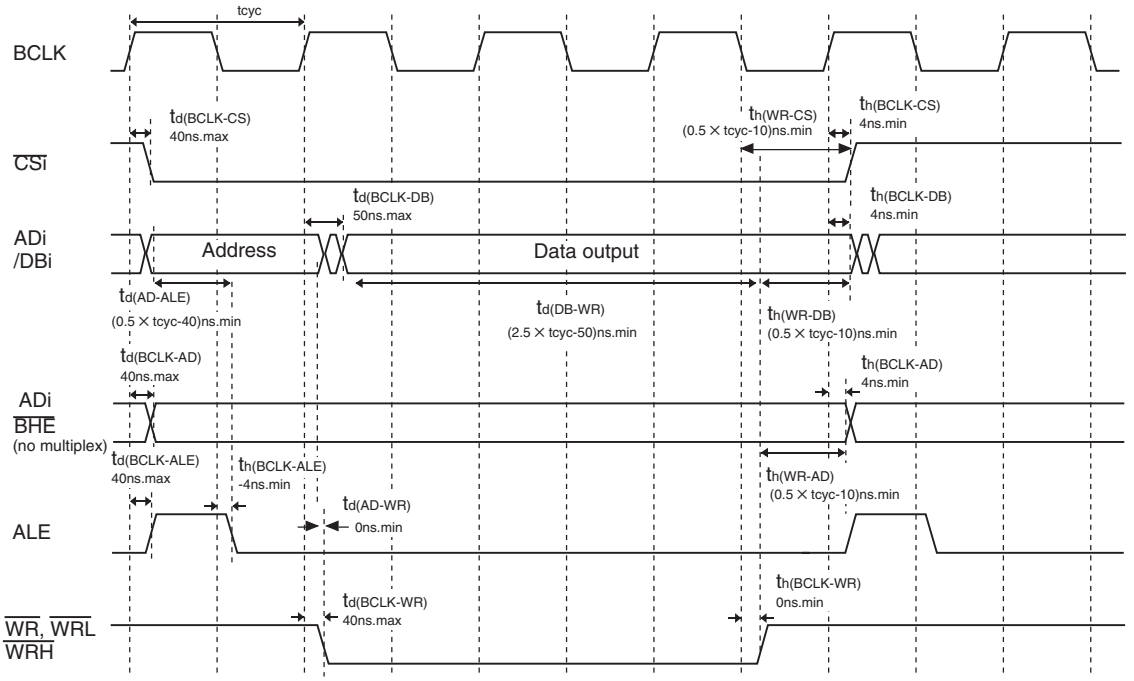
Memory Expansion Mode and Microprocessor Mode — VCC = 3.3 V

(For 3-wait setting, external area access and multiplexed bus selection)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.19 Timing Diagram (8)